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(12) **United States Design Patent**
Hisaishi et al.

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(54) **SEMICONDUCTOR CARRIER**

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(73) Assignee: **Yamaichi Electronics Co., Ltd.**, Tokyo (JP)

(**) **Term:** **14 Years**

(21) **Appl. No.:** **29/210,045**

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(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/182; 257/666, 257/669, 675, 676; 324/755

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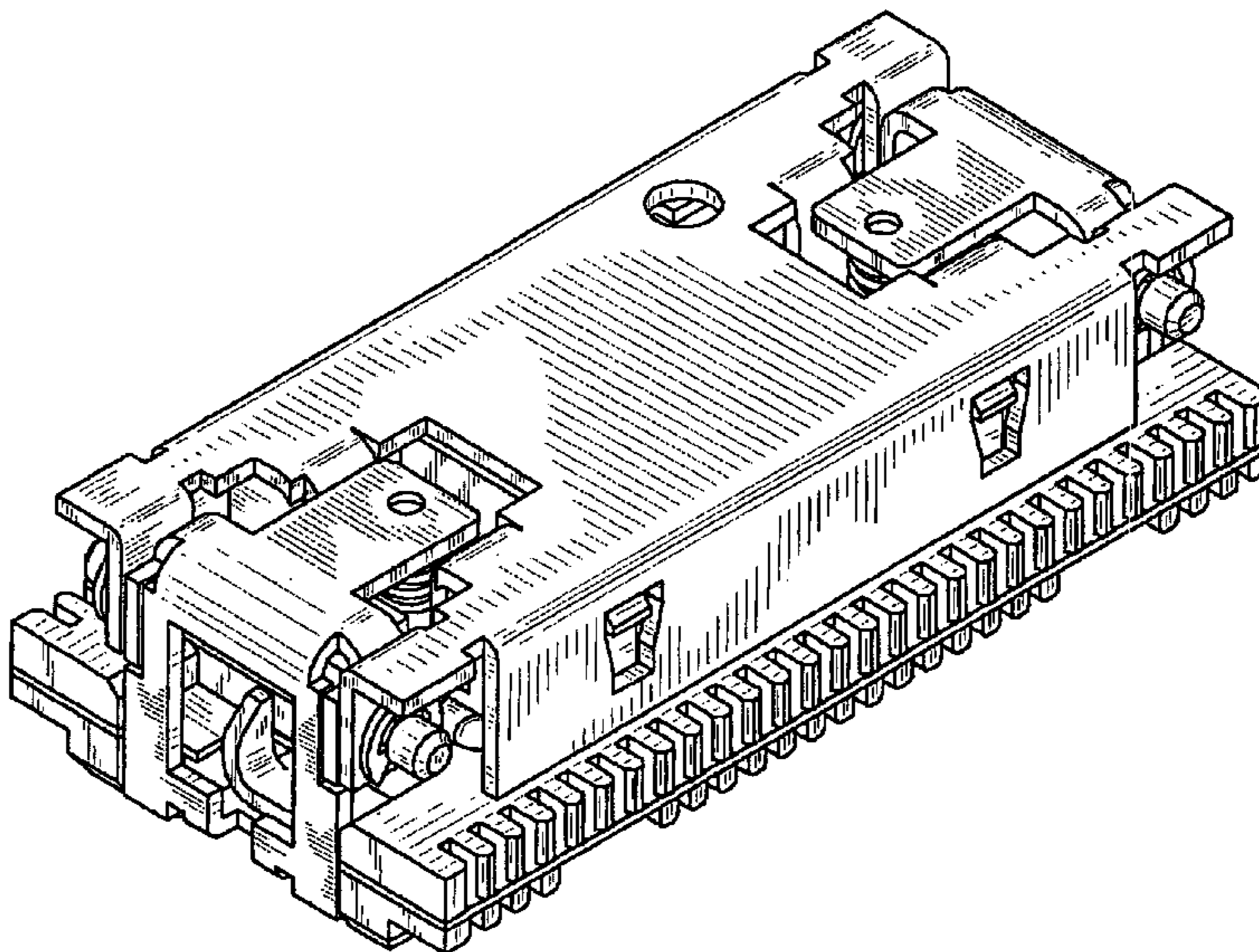
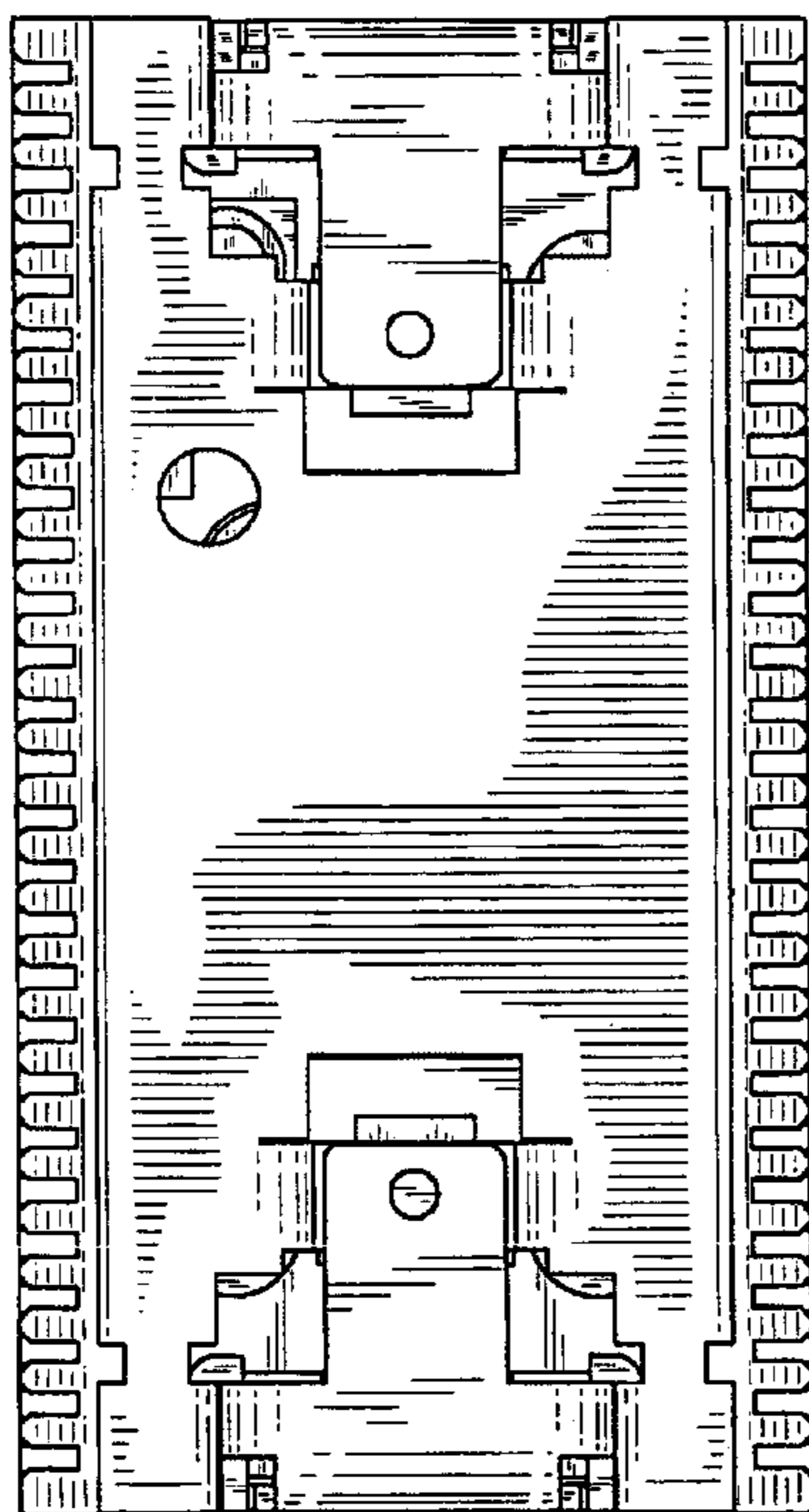
(57) **CLAIM**

The ornamental design for a semiconductor carrier, as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of a semiconductor carrier of our new design in its entirety;
FIG. 2 is a bottom plan view of our new design;
FIG. 3 is a right end view of our new design;
FIG. 4 is a left end view of our new design;
FIG. 5 is a front view of our new design;
FIG. 6 is a rear view our new design; and,
FIG. 7 is a left, front perspective view of our new design.

1 Claim, 7 Drawing Sheets



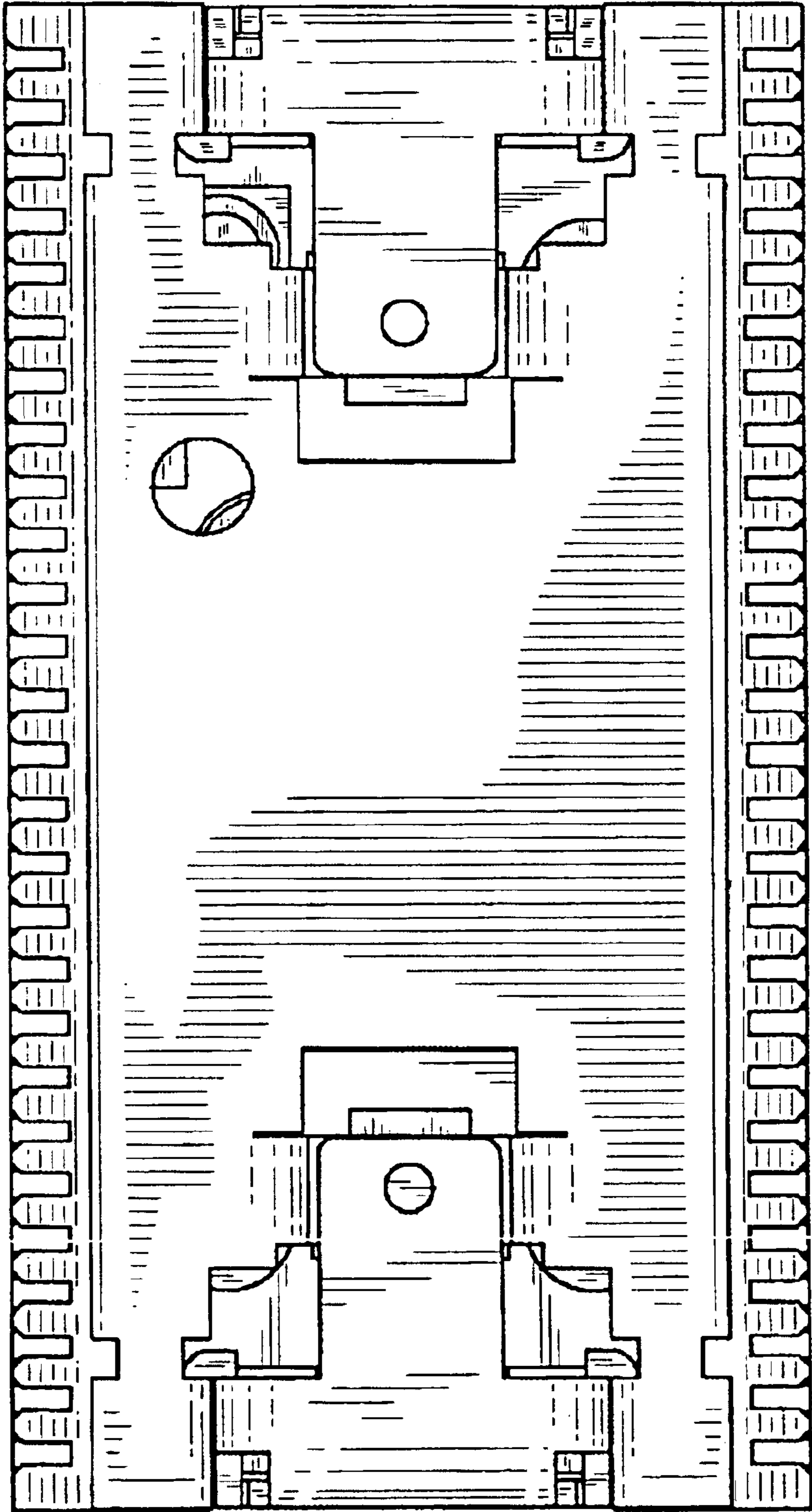


FIG. 1

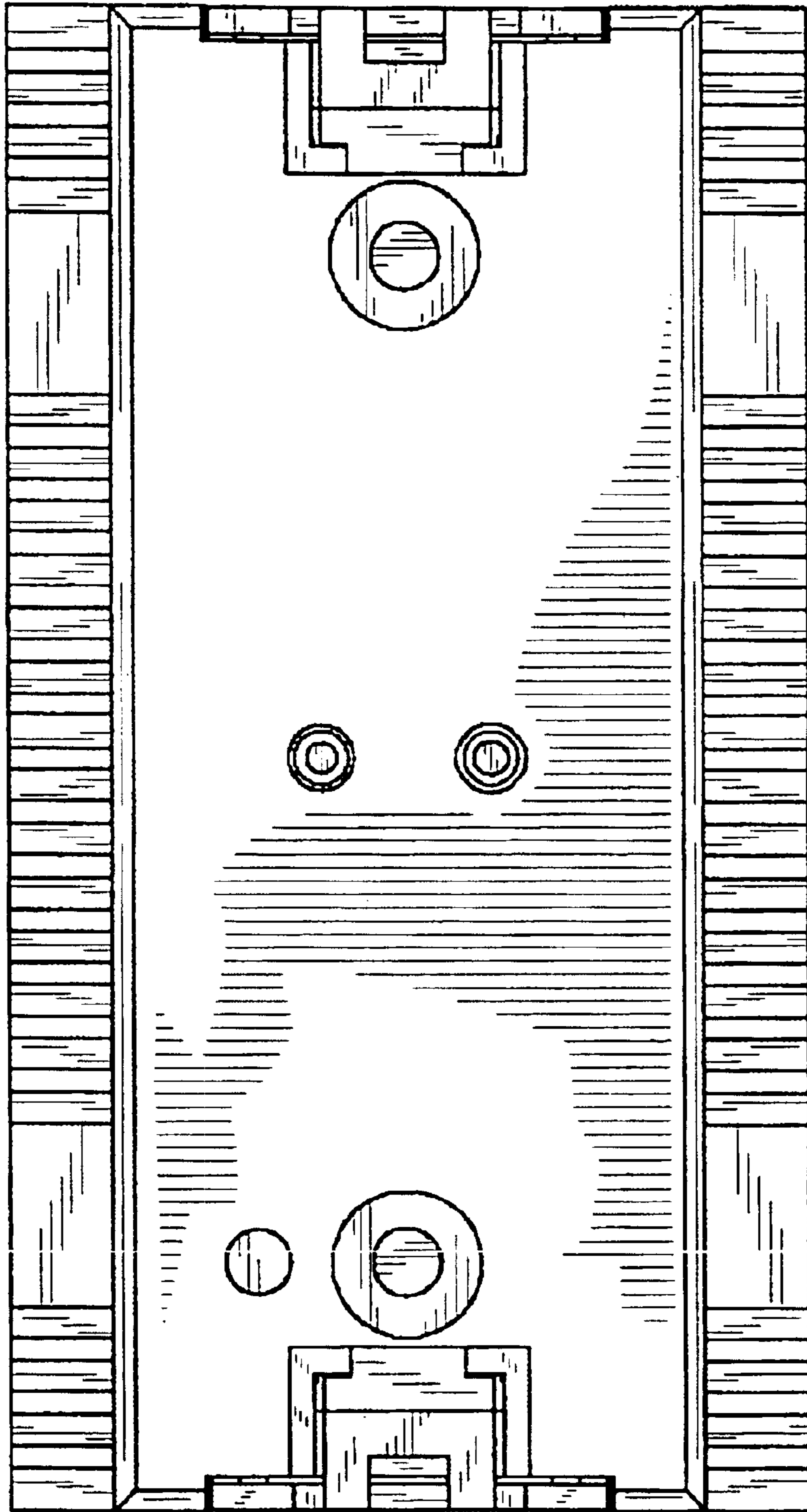


FIG. 2

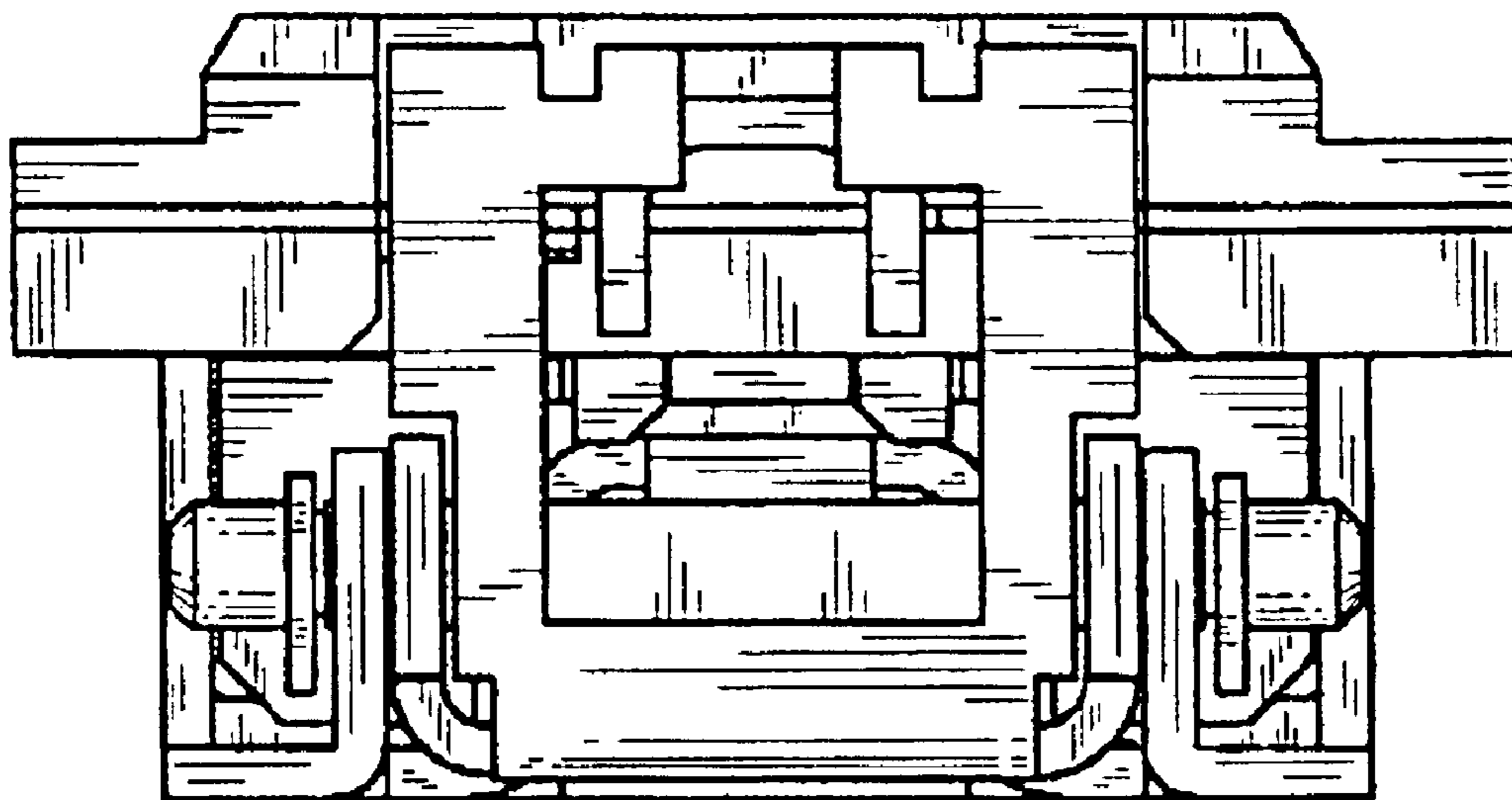


FIG. 3

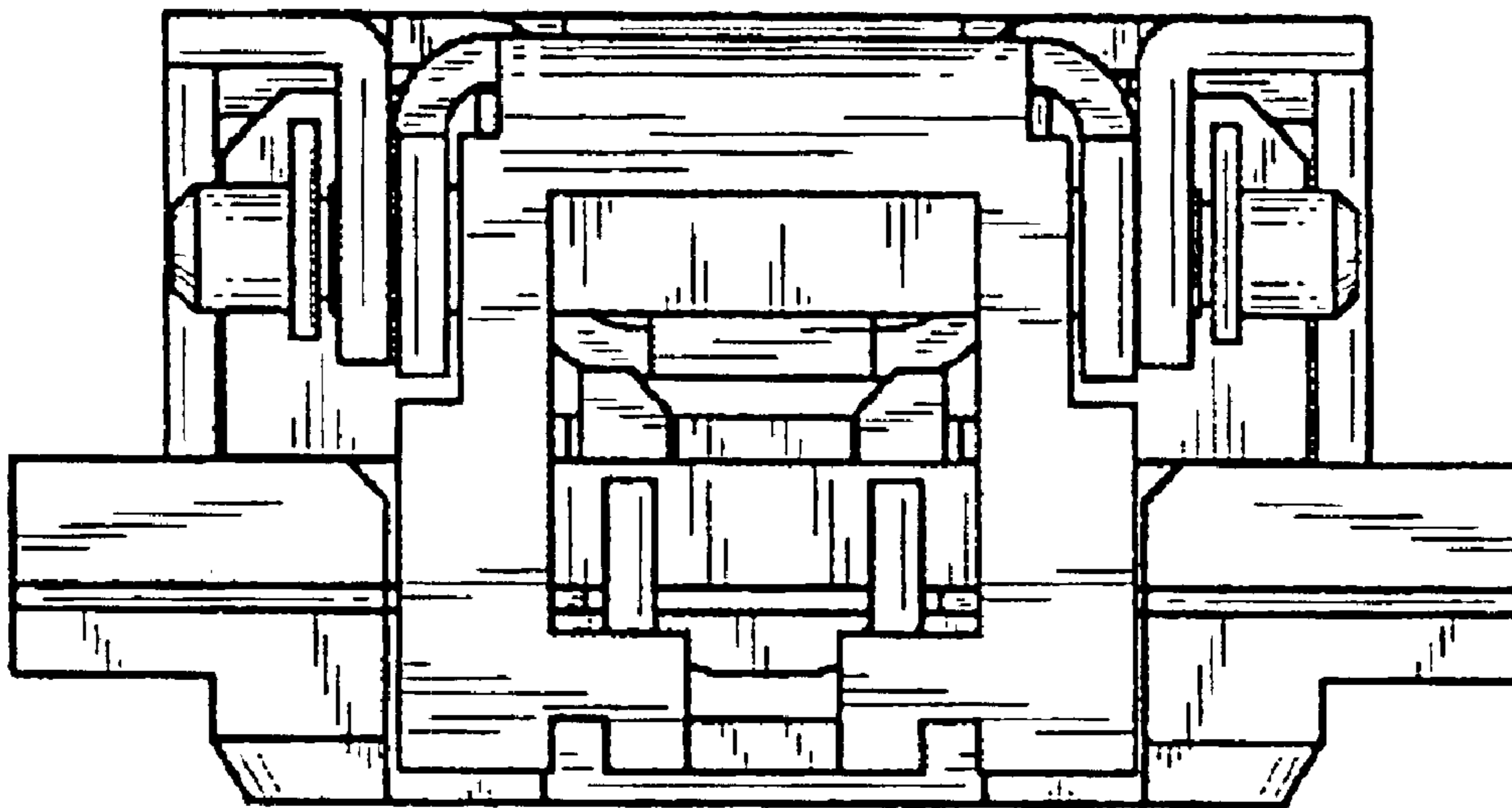


FIG. 4

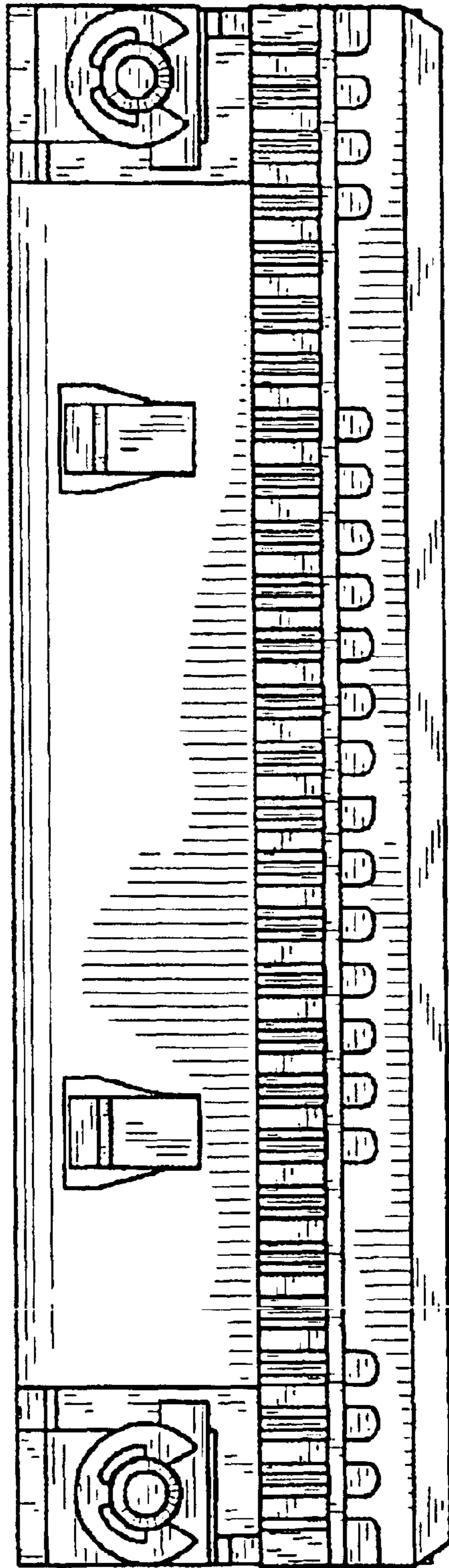


FIG. 5

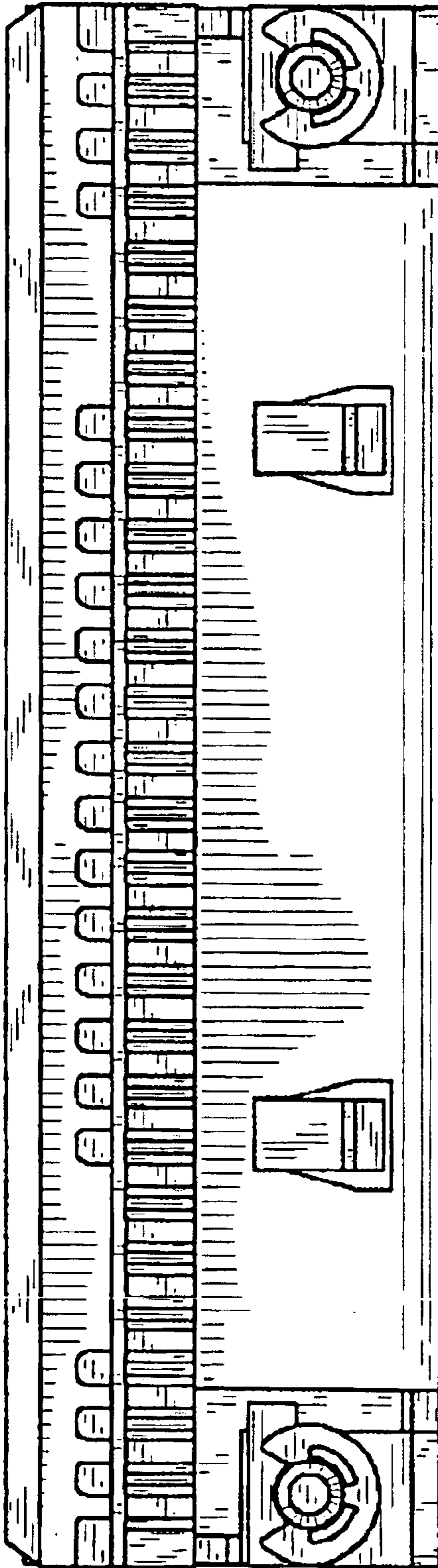


FIG. 6

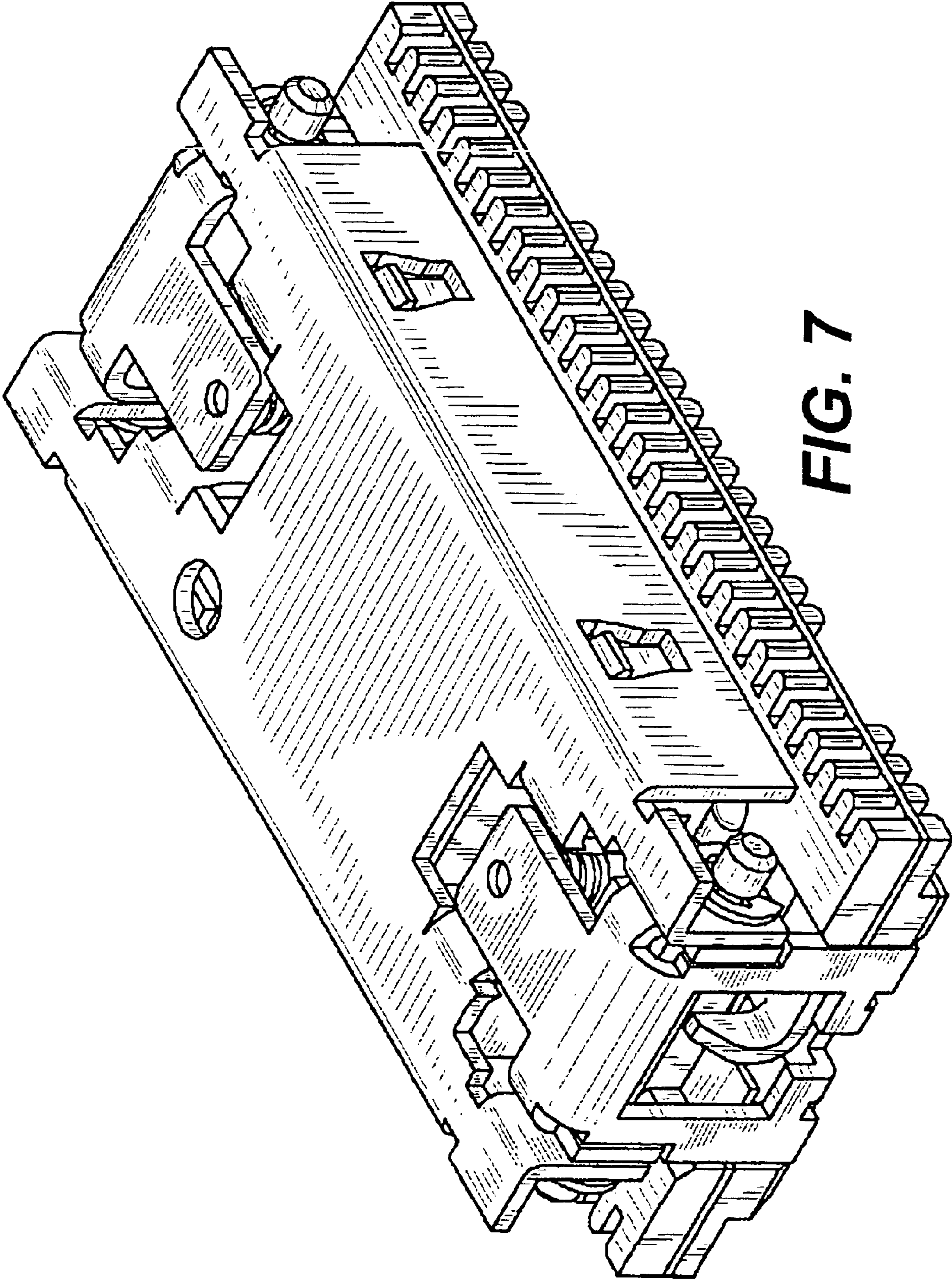


FIG. 7